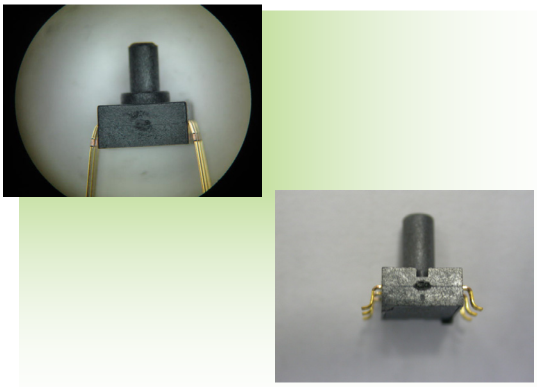
Data Sheet-DIP/SOP

MEMS Pressure Sensor



APPLICATIONS

- Medical InstrumentationAltimeterWeather ForecastTire GaugePressure GaugeIndustrial SensorHome Appliances

DEFINITION

Assembly type:

1.DIP (Dual In Line Package)

2.SOP (Small Outline Package)

FEATURES

- Low Cost
- Gauge Version and Absolute Version

DESCRIPTION

Lingsen MEMS Pressure Sensor is a wire bonded and Lid seal on pre-mold lead-frame in package. MEMS(Micro Electro-Mechanical system) pressure sensor can be used in medical Instrumentation products etc..

- Constant Current or Constant Voltage Drive
- High Output
- Wide Pressure Range Available from 1psi to 60psi

RELIABILITY

NA

SPECIFICATIONS

Gold Wire: 99.99%Au.

Pre-Mold Compound: PPS/LCP

Plating: NiAu

Marking: Laser

Packing: Antistatic Tube

Data Sheet-DIP/SOP

THERMAL PERFORMANCE

Package	Body size (mm)	Pad size (mm)	Die size (mm)	Thermal Performance ψja (℃/W)

DIP06UNS	7.2x7.2	3.5x3.1	1.9x1.9x 0.54
SOP06UNSP	7x7	3.5x3.1	1.9x1.9x 0.54

Note: Simulated with JEDEC Standard 4-layer test board and 51-series under still air condition, ambient temperature 45℃

ELECTRICAL PERFORMANCE

Package	Body size (mm)	Pad size (mm)	Frequency (MHz)	Self inductance (nH)	Self capacitance (pF)	Resistance (mohm)
DIP06UNS	7.2x7.2	3.5x3.1				
SOP06UNSP	7x7	3.5x3.1				

Note: Results are simulated. Data is available through 1GHz. Follow JEDEC standard 51-series.

CROSS-SECTION